

**Resin-moulded semiconductor hybrid module and manufacturing method thereof**

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Inventor(s): KAMIMURA NORITAKA (JP); TAKAHASHI MASAOKI (JP); SAEKI JUNICHI (JP); TAMBA AKIHIRO (JP); YAMADA KAZUJI (JP); GOUDA MASAHIRO (JP); ISHII MAKOTO (JP); OGAWA TOSHIO (JP); SUZUKI KAZUHIRO (JP)

Applicant(s): HITACHI LTD (JP)

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☐ JP11233712, ☐ US6291880

Cited

Documents: EP0774782; US5699609; US5077595; JP8298299**Abstract**

A semiconductor device includes a main circuit part having a semiconductor device formed on an electrode plate (13) of a lead frame and a control circuit part having protective functions, which is integrally molded by a resin mold part (30) into an integral mold structure. 

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